

#### 3662 4.5" x 6.5"

Circuit Pattern: Contacts Only 22/44 @ .156 Ctrs, Contacts:

Ni/Gold Width/Thick: 6.50"/.062" 4.50" Height: 16-Pin DIP Capacity: 50

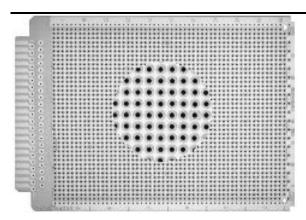
CEM-1. Material: Wire-Wrap Terminals: T44, T46, T49, T68

Wire-Wrap Socket Pins: R32 **Solder Connector:** R644 Extender: 3690 Rec. Card Cage: Series 13 Wire-Wrap Connector: R644-3 **Hole Diameter:** .042"

 Unrestricted component place ment over entire board surface

Layout paper and instructions included

Row and column legend provided



#### 4.5" x 6.5" 3662A6

**Circuit Pattern: Ground Plane** 22/44 @ .156" Ctrs, Contacts: Ni/Gold Width/Thick: 6.50"/.062"

Height: 4.50" 16-Pin DIP Capacity: 90 Material: CEM-1.

Wire-Wrap Terminals: Wire-Wrap Socket Pins Solder Connector:

Extender: 3690 Rec. Card Cage: Series 13 Wire-Wrap Connector: R644-3 **Hole Diameter:** .042"

• 0.085" diameter clearance area around holes

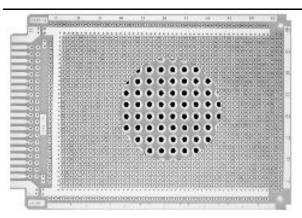
Ground plane on component side; wiring side has contacts only

 To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately

Plane surface is solder-coated for user convenience

Layout paper and instructions included

Row and column legend provided



#### 3662-9

## 4.5" x 6.5"

T44, T46, T49, T68

R32

R644

Circuit Pattern: Contacts: Ni/Gold

Width/Thick: Height:

16-Pin DIP Capacity:

Material:

Wire-Wrap Terminals: Wire-Wrap Socket Pins **Solder Connector:** Extender:

Rec. Card Cage: Wire-Wrap Connector: **Hole Diameter:** 

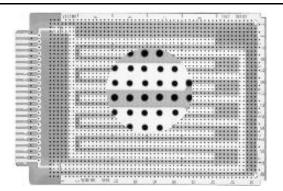
Pad-Per-Hole 22/44 @ .156" Ctrs,

6.50"/.062" 4.50" 48

FR4 Epoxy Glass T44, T46, T49, T68

R32 R644 3690 Series 13 R644-3 .042"

- 0.080" diameter, isolated solder pad around holes, both sides
- Pad and bus surfaces soldercoated for quick, convenient soldering
- Row and column legends provided
- Layout paper and instructions included



Note: Same as 3682-4 but without Ground Plane

#### 3682-2

# 4.5" x 6.5"

Circuit Pattern: Contacts:

Width/Thick: Heiaht:

16-Pin DIP Capacity: Material:

Wire-Wrap Terminals: Wire-Wrap Socket Pins: Solder Connector: Extender:

Rec. Card Cage: Wire-Wrap Connector: **Hole Diameter:** 

Interleaved Buses 22/44 @ .156" Ctrs, \*

Ni/Gold 6.50"/.062" 4.50"

24 CEM-1

T44, T46, T49, T68 R32 R644 3690 Series 13

R644-3 .042"

Bus pattern on wiring side, solder-coated for user convenience

Bus outline traced on component side to facilitate component placement

Mounts DIPs with 0.3", 0.4" and 0.9" lead spacing Unclad test point area at top of

board Layout paper and instructions

included Row and column legends

provided



#### 3682-4 4.5" x 6.5"

Circuit Pattern: Interleaved Bus/ Ground Plane Contacts: 22/44 @ .156" Ctrs.

**Contacts:** 22/44 @ .156" Ctr. Ni/Gold

 Width/Thick:
 6.50"/.062"

 Height:
 4.50"

 16-Pin DIP Capacity:
 24

 Material:
 CEM-1

Wire-Wrap Terminals: T44, T46, T49, T68

 Wire-Wrap Socket Pins:
 R32

 Solder Connector:
 R644

 Extender:
 3690

 Rec. Card Cage:
 Series 13

 Wire-Wrap Connector:
 R644-3

 Hole Diameter:
 .042"

 Power bus in rows across component side; overall ground plane on wiring side

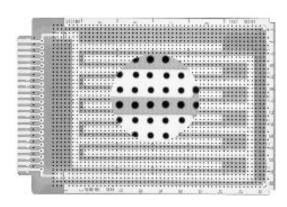
 0.085" etched clearance area around each hole on ground plane side

 Bus and plane surfaces solder coated for user convenience

 To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately

 Layout paper and instructions included

 Row and column legends provided



### 3677-2 4.5" x 6.5"

Circuit Pattern: 3-Hole Solder Pad
Contacts: 22/44 @ .156" Ctrs.
Ni/Gold

 Width/Thick:
 6.50"/.062"

 Height:
 4.50"

 16-Pin DIP Capacity:
 12

 Material:
 CEM-1

Wire-Wrap Terminals: T44, T46, T49, T68

Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

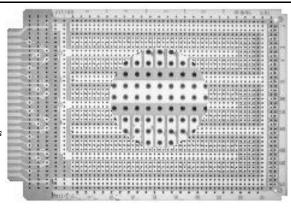
 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads

 Voltage/ground buses interleaved between pad areas on wiring side

 Row and column legends provided

 Test point area, with solder pads around holes, provided along back edge of board

 Layout paper and instructions included



### 4112-4 4.5" x 6.5"

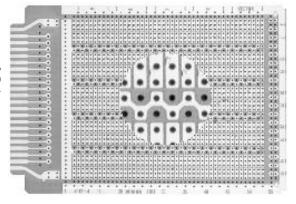
Circuit Pattern: 3-Hole Solder Pad Contacts: 22/44 @ .156" Ctrs,

Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 25
Material: CEM-1

Wire-Wrap Terminals: T44, T46, T49, T68

Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

- Continuous ground plane on component side with 0.085" clearance pad around each hole
- 3-hole solder pads (0.28 x 0.080") for interconnecting multiple component leads
- Row and column legends provided
- Layout paper and instructions included



# 3662-2 4.5" x 9.6"

Circuit Pattern: Contacts Only Contacts: 22/44 @ .156" Ctrs,

Ni/Gold
Width/Thick: 9.60"/.062"
Height: 4.50"
16-Pin DIP Capacity: 90
Material: CEM-1

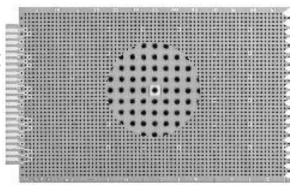
Wire-Wrap Terminals: T44, T46, T49, T68

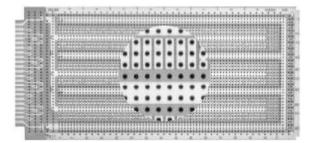
Wire-Wrap Socket Pins: R32
Solder Connector: R644
Extender: 3690-6
Rec. Card Cage: Series 14
Wire-Wrap Connector: R644-3
Hole Diameter: .042"

 Unrestricted component placement over entire board surface

 Row and column legends provided

Layout paper and instructions included





4.5" x 9.6" 3677

Circuit Pattern: 3-Hole Solder Pad Contacts:

Ni/Gold Width/Thick: 9.60"/.062" Height: 4.50" 16-Pin DIP Capacity: 21

Material: CEM-1

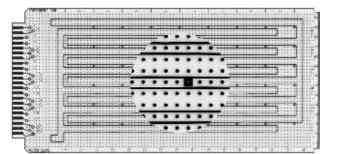
Wire-Wrap Terminals: T44, T46, T49, T68

Wire-Wrap Socket Pins R32 **Solder Connector:** R644 Extender: 3690 Rec. Card Cage: Series 14 R644-3 Wire-Wrap Connector:

22/44 @ .156" Ctrs, 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads Row and column legends

provided Layout paper and instructions

included



4.5" x 9.6" 3682

Circuit Pattern: Interleaved Buses Contacts:

Width/Thick: 9.60"/.062" Height: 4.50" 16-Pin DIP Capacity: 48

Material: CEM-1

Wire-Wrap Terminals: Wire-Wrap Socket Pins R32 Solder Connector: R644 Extender: 3690-6

Rec. Card Cage: Series 13 Wire-Wrap Connector: R644-3 **Hole Diameter:** .042"

22/44 @ .156 Ctrs,

• Etched bus pattern on wiring solder-coated for user convenience

Bus outlines traced on component side

 Mounts DIPs with 0.3", 0.4" and T44, T46, T49, T68 0.9" lead spacings

Layout paper and instructions included

· Row and column legends provided

4112

**Circuit Pattern:** Contacts:

Width/Thick: Height:

16-Pin DIP Capacity:

Material:

Wire-Wrap Terminals: Wire-Wrap Socket Pins: **Solder Connector:** Extender:

Rec. Card Cage: Wire-Wrap Connector: Hole Diameter:

4.5" x 9.6"

3-Hole Solder Pad • Zig-zag bus pattern on wiring Ni/Gold 9.60"/.062"

4.50" 40

FR4 Epoxy Glass • T44, T46, T49, T68

R32 R644 3690-6 Series 13

R644-3 .042"

22/44 @ .156" Ctrs, side provides access to voltage or ground at alternating hole

3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads

Continuous ground plane on component side with 0.085" etched clearance area around each hole

Layout paper and instructions included

Row and column legends provided



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